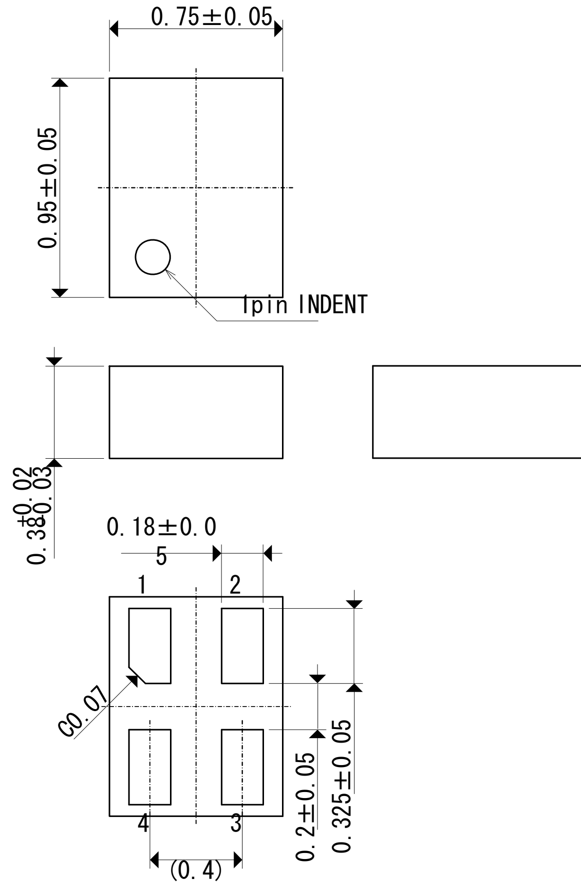
Packaging Information / Reference Pattern Layout Dimensions

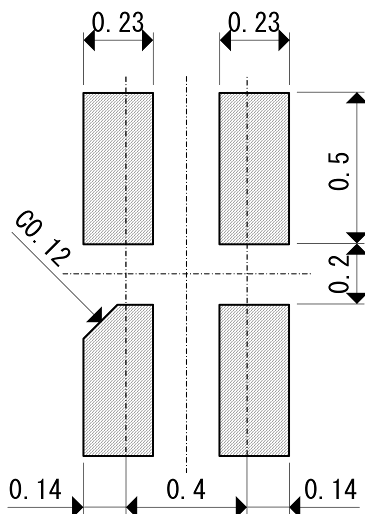
●USPN-4B02

■Packaging Information

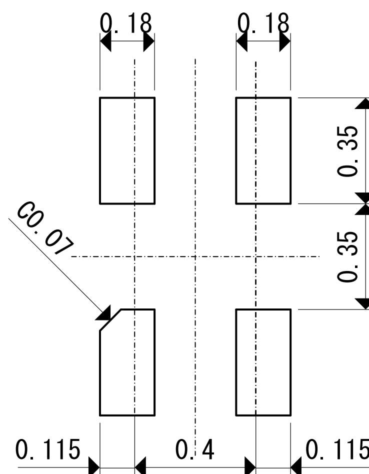
Unit: mm



■Reference Pattern Layout Dimension



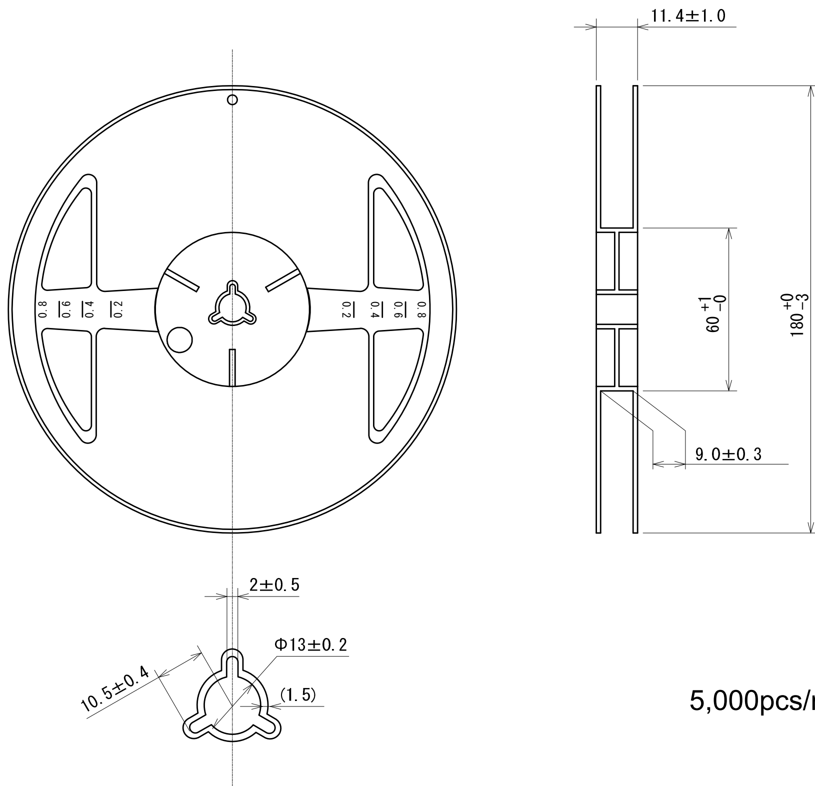
Reference metal mask design



Taping Specifications

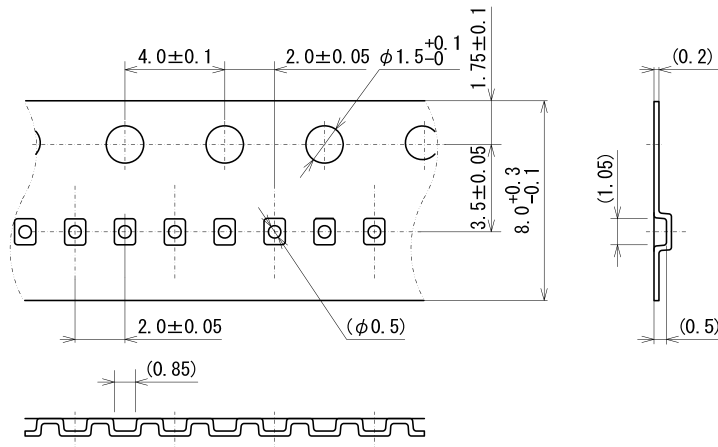
●USPN-4B02 Reel

Unit: mm

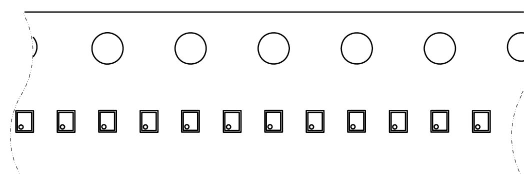


5,000pcs/reel

●Taping Specifications



direction of feed



R Type :[Device orientation : Right]

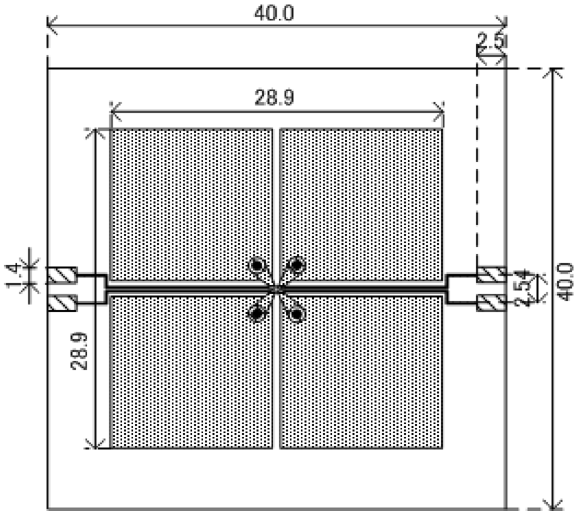
Standard feed

● USPN-4B02 Power Dissipation

Power dissipation data for the USPN-4B02 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40 x 40 mm (1600 mm^2 in one side)
Copper (Cu) traces occupy 50% of the front and 50% of the back.
The copper area is divided into four block,
one block is 12.5% of total.
The USPN-4 package has for terminals.
Each terminal connects one copper block in the front
and one in the back.
Material: Glass Epoxy (FR-4)
Thickness: 1.6 mm
Through-hole: 4 x 0.8 Diameter

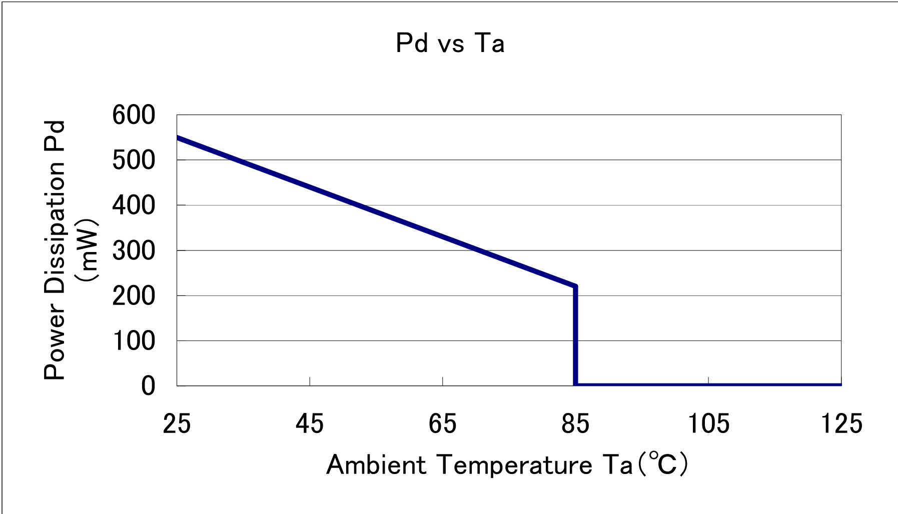


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125℃)

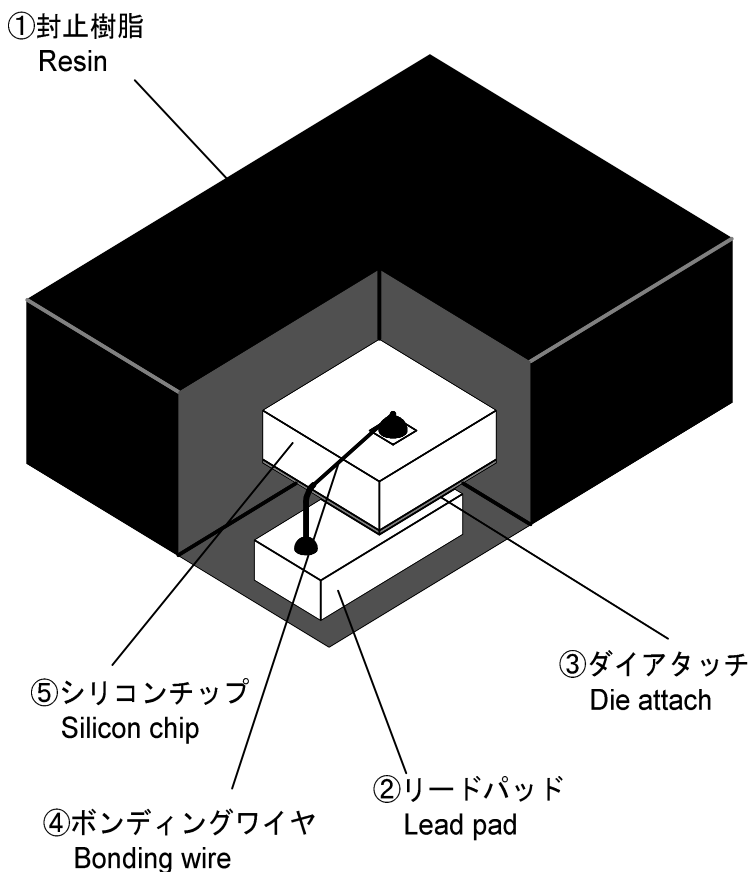
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance(℃/W)
25	550	181.82
85	220	



TOIREX

USPN-4B02構造図
USPN-4B02 Perspective

RoHS対応品
RoHS Compliance



項 目 item		材 料 material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードパッド Lead pad	ニッケル Nickel	
	端子処理 Outer pad plating	Auメッキ Gold plating	
③	ダイアタッチ Die attach	ダイアタッチフィルム Die attach film	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking